



#### 100V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
100V	$23m\Omega$ @ $V_{GS} = 10V$	41.2A
	$30m\Omega$ @ $V_{GS} = 6V$	36.1A

## Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

## **Applications**

- Power Management Functions
- DC-DC Converters
- Backlighting

## **Features**

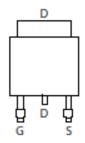
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Minimizes Power Losses
- Low Q<sub>G</sub> Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

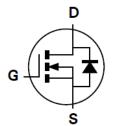
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)







Pin Out Top View



**Equivalent Circuit** 

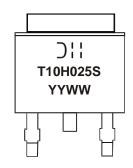
### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMT10H025SK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead\_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



Oll = Manufacturer's Marking T10H025S = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)

July 2018



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	100	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current, $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$		I <sub>D</sub>	41.2 32.9	А
Pulsed Drain Current (10µs Pulse, T <sub>C</sub> =+25°C, Package Limited)		I <sub>DM</sub>	160	Α
Maximum Continuous Body Diode Forward Current (Note 6)		Is	45	Α
Pulsed Body Diode Forward Current (10µs Pulse, T <sub>C</sub> =+25°C, Package Limited)		I <sub>SM</sub>	160	Α
Avalanche Current, L = 0.1mH (Note 8)		I <sub>AS</sub>	7.5	Α
Avalanche Energy, L = 0.1mH (Note 8)		E <sub>AS</sub>	2.8	mJ

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P <sub>D</sub>	1.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>0JA</sub>	81	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	2.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	46	°C/W
Thermal Resistance, Junction to Case		R <sub>0</sub> JC	2.1	C/VV
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		l .		1		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	$V_{DS} = 80V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)					•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	2	_	4	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Statio Drain Source On Registeres		_	17.8	23	0	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	22.9	30	mΩ	$V_{GS} = 6V, I_D = 20A$
Diode Forward Voltage	V <sub>SD</sub>	_	0.9	1.3	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C <sub>iss</sub>	_	1544	_		$V_{DS} = 50V, V_{GS} = 0V$ f = 1MHz
Output Capacitance	C <sub>oss</sub>	_	250	_	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	20.4	_		
Gate Resistance	Rg	_	1.26	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	21.4	_		V 50V I 20A
Total Gate Charge (V <sub>GS</sub> = 6V)	Qg	_	13.4	_	C	
Gate-Source Charge	Q <sub>gs</sub>	_	4.6	_	nC	$V_{DD} = 50V, I_D = 20A$
Gate-Drain Charge	Q <sub>gd</sub>	_	6.0	_		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	8.2	_		
Turn-On Rise Time	t <sub>R</sub>	_	11.2	_		$V_{DD} = 50V, V_{GS} = 10V,$
Turn-Off Delay Time	t <sub>D</sub> (OFF)	_	27.5	_	ns	$I_D = 20A$ , $R_g = 11\Omega$
Turn-Off Fall Time	t <sub>F</sub>	_	13.7	_		
Reverse Recovery Time	t <sub>RR</sub>	_	37.5	_	ns	
Reverse Recovery Charge	Q <sub>RR</sub>	_	50.9	_	nC	$I_F = 20A$ , di/dt = 100A/ $\mu$ s

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

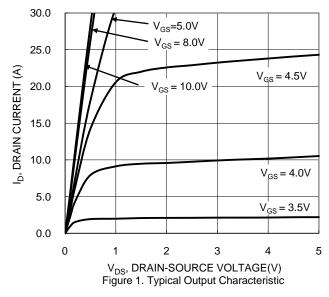
<sup>6.</sup> Thermal resistance from junction to soldering point (on the exposed drain pad).

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>8.</sup> Guaranteed by design. Not subject to product testing.







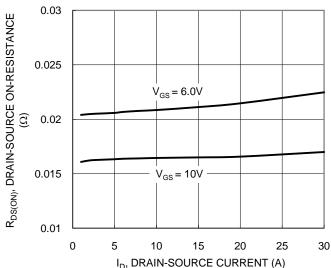
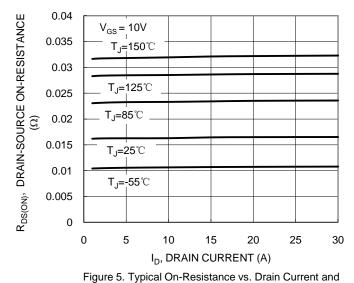
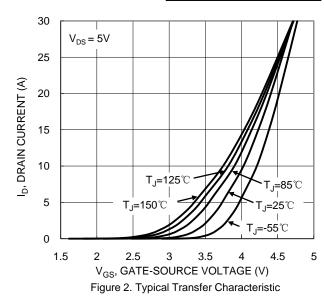


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



Junction Temperature



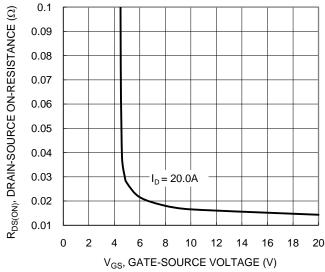


Figure 4. Typical Transfer Characteristic

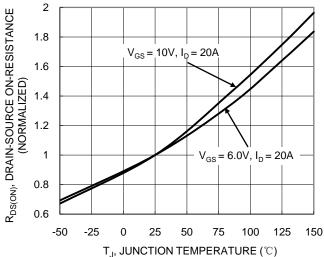


Figure 6. On-Resistance Variation with Junction Temperature





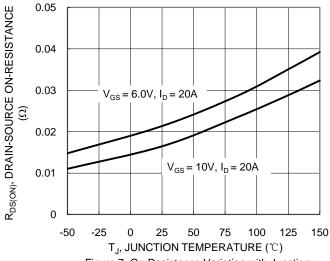


Figure 7. On-Resistance Variation with Junction Temperature

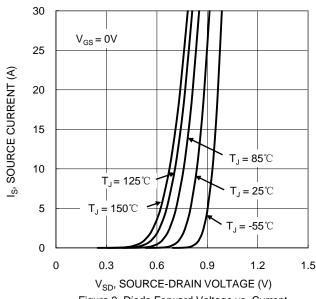


Figure 9. Diode Forward Voltage vs. Current

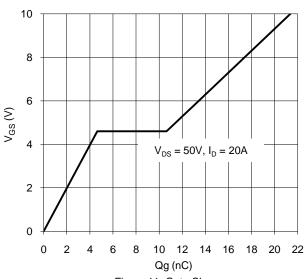


Figure 11. Gate Charge

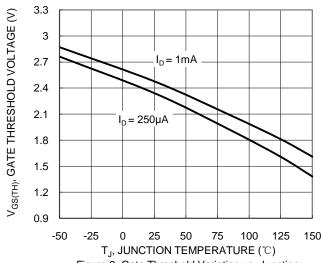
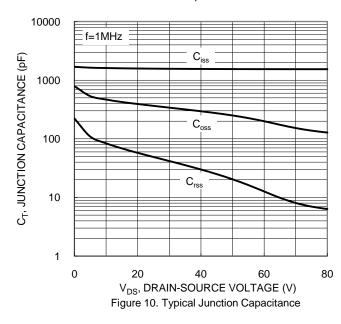


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R<sub>DS(ON)</sub> Limited 100 ID, DRAIN CURRENT (A) 10 T<sub>J(Max)</sub> = 150°C <sub>W</sub> =10ms T<sub>C</sub> = 25 °C Single Pulse 0.1 P<sub>W</sub> =100ms DUT on Infinite DC Heatsink  $V_{GS} = 10V$ 0.01 0.1 10 100 1000 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



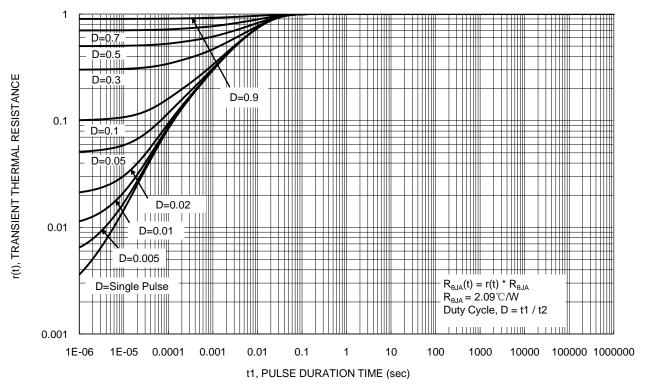
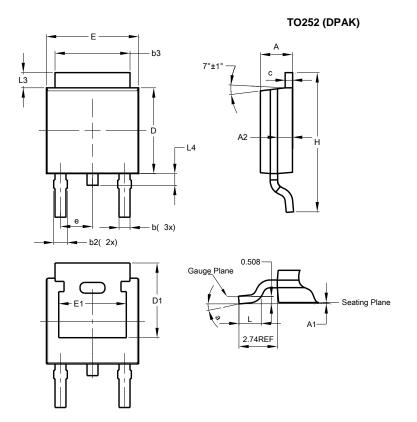


Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

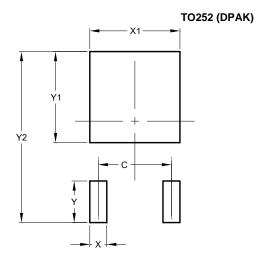
Please see http://www.diodes.com/package-outlines.html for the latest version.



	TOOLO	/DDAI	^		
TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
<b>A1</b>	0.00	0.13	0.08		
<b>A2</b>	0.97	1.17	1.07		
q	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
П	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
٦	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Y	2.600		
Y1	5.700		
Y2	10 700		



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